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3.0x1.0mm RIGHT ANGLE SMD CHIP LED **LAMP**



ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

Part Number: APFA3010LSEEZGKQBKC

Hyper Red Green Blue

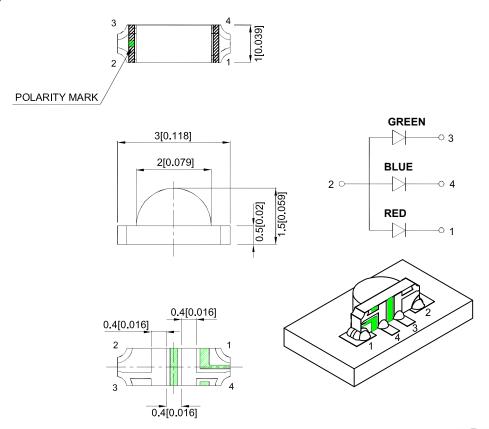
Features

- 3.0x1.5x1.0mm right angle SMD LED, 1.0mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Tinned pads for improved solderability.
- Low current IF=2mA operating.
- RoHS compliant.

Descriptions

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- The Blue source color devices are made with InGaN on Sapphire Light Emitting Diode.
- Electrostatic discharge and power surge could damage
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



SPEC NO: DSAO4451

APPROVED: Wynec

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.2(0.008") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Тур.	201/2
APFA3010LSEEZGKQBKC	Hyper Red (AlGaInP)		6	15	120°
	Green (InGaN)	Water Clear	20	60	
	Blue (InGaN)		4	10	

Notes:

- θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 Luminous intensity / luminous Flux: +/-15%.
 Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green Blue	630 515 460		nm	IF=2mA
λD [1]	Dominant Wavelength	Hyper Red Green Blue	621 525 465		nm	Ir=2mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green Blue	20 35 25		nm	IF=2mA
С	Capacitance	Hyper Red Green Blue	25 45 100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red Green Blue	1.8 2.65 2.65	2.1 3.1 3.1	V	IF=2mA
lr	Reverse Current	Hyper Red Green Blue		10 50 50	uA	VR=5V

Notes:

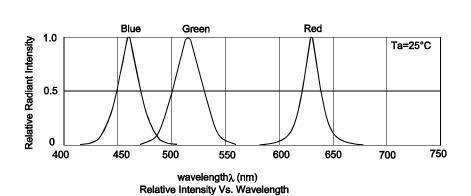
- Wavelength: +/-1nm.
 Forward Voltage: +/-0.1V.
 Wavelength value is traceable to the CIE127-2007 compliant national standards.
 Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

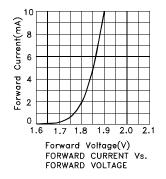
Parameter	Hyper Red	Green	Blue	Units		
Power dissipation	63	77.5	93	mW		
DC Forward Current	30	25	30	mA		
Peak Forward Current [1]	195	150	150	mA		
Electrostatic Discharge Threshold (HBM)	3000	450	250	V		
Reverse Voltage		V				
Operating Temperature	-40°C To +85°C					
Storage Temperature	-40°C To +85°C					

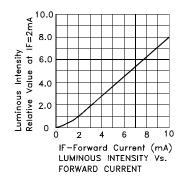
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

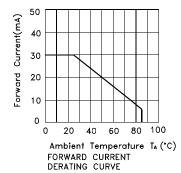
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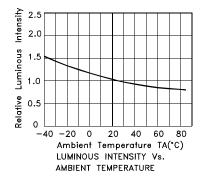


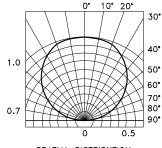
APFA3010LSEEZGKQBKC Hyper Red







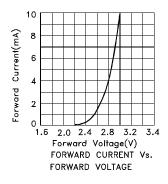


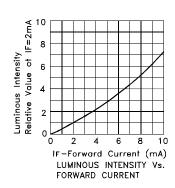


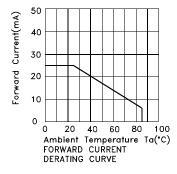
SPATIAL DISTRIBUTION

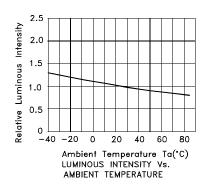
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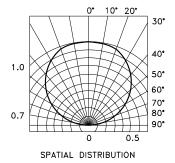
Green





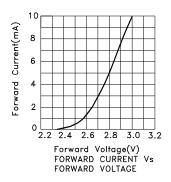


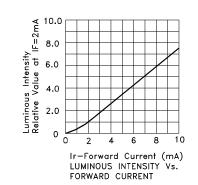


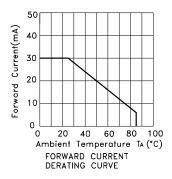


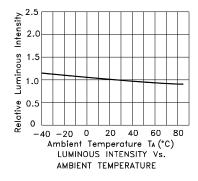
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Blue



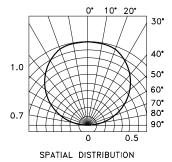






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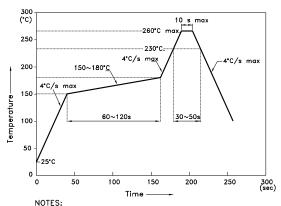


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APFA3010LSEEZGKQBKC

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

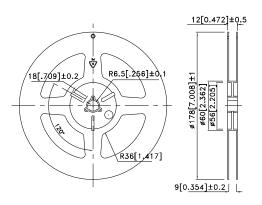
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 - 3.Number of reflow process shall be 2 times or less.

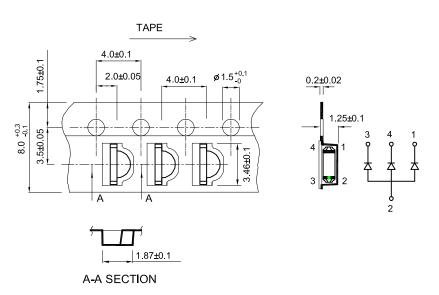
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

0.4 0.4

Tape Dimensions (Units : mm)

Reel Dimension



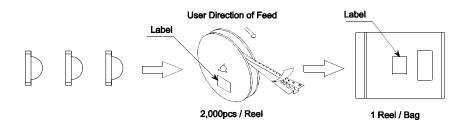


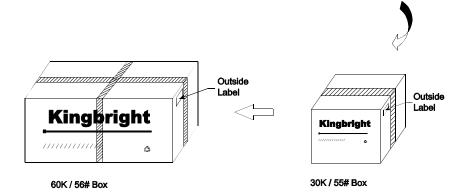
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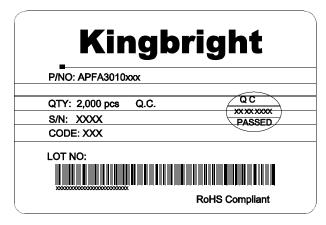
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PACKING & LABEL SPECIFICATIONS

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